	Material Comp © Copyright 2005. Il international and Par	osition Dec PC, Bannockb American co	claration ourn, Illinois. A opyright conver	Il rights reserved untions.	inder both	This docume level parts, th	ent is a declarati he declaration e	on of the subst ncompasses al	ances within l lower level	the manufactur materials for w	er listed ite hich the m	em. Note: if anufacturer	f the item is an as has engineering	sembly with lowe responsibility.
1752-21.1	IPC Web Site for Inf http://www.ipc.org/	PC-1752 Standard Form Type * Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materia				als and Mfg Information				
Supplie	r Information													
Company	name*	Company unique ID			1	Unique ID Authority				Response Date*				
On Semic	onductor										2021-02-03			
Contact N	lame	Title - Contact			]	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorize	ed Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*				
Product-l	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number Mfr Item   2SC4135						Effective Date	te Version Manufacturing Site		v	Veight*	UOM	Unit Type	
							2021-02-03 CNG		3	25.95	mg	Each		
/Ianufa	cturing Proccess Informat	tion					·	•					I	I
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-		J-STD-020 MSL	Rating	Peak Process Body T		ody Temperature Max Time at Peak		Temperature Number of		er of Reflow Cyc	les
contains Bi		CU Alloy NA		NA		0 C		30	<b>30</b> seco		ls 3			
omments	8													
or more	information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed									
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl			mass (1000 PPM) in homogeneous material for: Lead d Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl									
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of									
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted									
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).														
Exemption List Version	EL-2011/534/EU													
Declaration Signature														
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.														
Supplier Digital Signature	astislav Drska	Le												

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.67	mg	Supplier	Silicon (Si)	7440-21-3		0.67	mg
Die Attach Solder	0.31	mg	Supplier	Silver (Ag)	7440-22-4		0.0078	mg
			А	Lead (Pb)	7439-92-1	7a	0.2868	mg
			Supplier	Tin (Sn)	7440-31-5		0.0155	mg
ead Frame	191.37	mg	Supplier	Silver (Ag)	7440-22-4		0.3827	mg
			Supplier	Tin (Sn)	7440-31-5		0.2679	mg
			Supplier	Copper (Cu)	7440-50-8		190.7193	mg
Mold Compound-Black	k 130.08	mg		Brominated epoxy resin	proprietary data		1.8211	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		5.8536	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.1707	mg
			Supplier	Carbon Black (C)	1333-86-4		1.3008	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		97.56	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		22.1136	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2602	mg
Plating	3.34	mg	В	Bismuth (Bi)	7440-69-9		0.02	mg
			Supplier	Tin (Sn)	7440-31-5		3.32	mg
Wire Bond - Au	0.18	mg	Supplier	Gold (Au)	7440-57-5		0.18	mg